2026 International Applied Computational Electromagnetics Society Symposium (ACES-China 2026)

August 21-24, 2026, Qingdao, China

www.aces-china2026.org

Call For Papers

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2026 International Applied Computational Electromagnetics Society Symposium (ACES-China 2026) is the International Applied Computational Electromagnetics Society's annual conference on Applied Computational Electromagnetics for Various Applications in Electromagnetic Science and Engineering. We warmly welcome you to join the **ACES-China 2026** in Qingdao, **August 21-24, 2026**.

ACES-China is the continuation of a series of annual conference held in Suzhou (2017), Beijing (2018), Nanjing (2019), Chengdu (2021), Xuzhou (2022), Hangzhou (2023) and Xi'an (2024), Huangshan (2025).

Topics

The topics include, but are not limited to, the following technical areas:
Computational Methods, EM Theory and Modeling: Integral equation/differential equation, time domain/frequency domain, hybrid and multi-physics, low frequency and high frequency techniques, optimization techniques, quantum EM, Bio-EM, parallel and distributed computations, AI in EM;

Antennas and Propagation: Small Antennas, wideband and multiband antennas, antenna arrays, dielectric resonator antennas, MIMO antennas, RFID antennas, space and satellite antennas, wearable antennas, bio-antennas, scattering and propagation, AI for antennas and arrays;

Passive Components and Packaging: Planar passive components, non-planar passive components, integrated passive circuits, microwave/RF filters, resonators, power combiners/dividers, waveguides and transmission lines, passive device modelling and simulations, microwave acoustic, ferrite, ferroelectric, phase-change, MEMS components, RF MEMS, LTCC devices, MCMs, metamaterials and EBG structures, liquid crystal polymer, 3D and inkjet printing, fan-out wafer packaging, glass substrate and others;

Active Devices and Circuits: Semiconductor devices, low-noise devices and circuits, high-power devices and circuits, wide bandgap devices, device modelling and characterization, MMICs, RFICs, millimeter and terahertz wave devices and circuits, RF circuits for quantum computing, AI for active circuits, and others;

Nano-Photonics and Quantum Devices: Photonic integrated circuits, photonic crystals and nanocavities, 2D materials, III-V and wide bandgap materials, emerging quantum devices and systems, nonlinear and ultrafast nanophotonics, perovskite nanophotonics and optoelectronics;

Metamaterials and Non-Hermitian Physics: Metamaterials, metaphotonics and intelligent metastructures, inverse design and machine-learning-assisted metastructures, adaptive smart materials, time varying metamaterials and metasurfaces, reconfigurable intelligent surfaces, non-hermitian physics, bound states in the continuum, exceptional points;

EMC and Signal/Power Integrity: EMC modeling and simulation, EMI mitigation and filtering, signal integrity for high-speed electronics, power integrity in heterogenous integrated circuits and systems;

Microwave Radar and Sensing: Microwave remote sensing, DoA, SAR algorithms and systems, inverse scattering, Radar techniques, Bio-Radar, AI for smart sensing, and others;

Microwave Measurement: Near-field techniques, microscopy, microwave measurement techniques, microwave properties characterization of materials, and others;

Systems and Applications: 5G and 6G systems, IoT/RFID systems IoTs, biomedicine, brain-machine interface, millimeter and terahertz wave systems, microwave photonics, AR/VR, MRI, satellite systems, low-attitude economics, wireless power transfer, security and health monitoring systems, autonomous driving systems and others.

Paper Submission

Prospective authors are invited to submit manuscripts in electronic (PDF) format. All papers must be written in English. Please submit **one-page abstract** or **full paper of up to 3 pages** including text, reference, and figures. All papers will be peer reviewed and will be included in **ACES** and indexed by **Engineering Index (EI)** after presentation at the conference.

Special Issue in Applied Computational Electromagnetic Society (ACES) Journal
Authors of all papers presented at the symposium are invited to submit an expanded version of their work to ACES Journal (SCI-indexed). Submissions that include correlations between computational and experimental results are particularly encouraged.

Awards

Three types of awards will be presented. For more details, please visit the conference website.

Technical Excellence Award
This award honors an individual for his/her exceptional career achievements in the relevant fields.

Young Scientist Awards
Awards will be presented to recognize outstanding young scientists presented at the conference.

Best Student Paper Awards
Best Student Paper Awards will be presented at the conference. To be eligible, the first author must be a full-time student and must present the paper in person at the conference. Students wishing to be considered for this award should indicate their interests during the paper submission process via EDAS.

Important Dates

Paper Submission Deadline	~~April 30, 2026~~	May 31, 2026
Notification of Acceptance	~~May 15, 2026~~	June 15, 2026
Final Paper Submission Deadline	~~May 31, 2026~~	June 30, 2026
Early-Bird Registration Deadline	~~June 15, 2026~~	July 15, 2026